

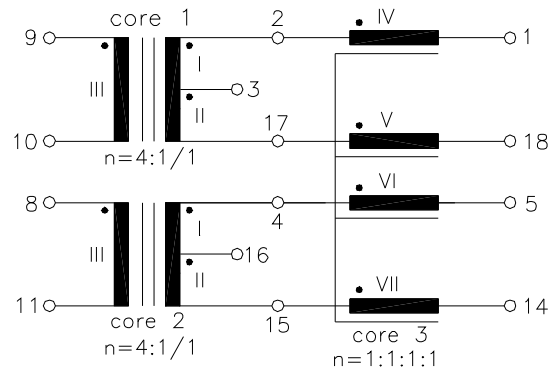
ISDN

UM MODEL NO.:	SPECIFICATION	REV.	
UT28615	S _O -Interface Module	B4	99/05

Characteristic data:

$R_{I+II} \approx 2.4\Omega (R_{CU.L})$
 $R_{III} \approx 5.0\Omega (R_{CU.IC})$
 $R_{IV \sim VII} \approx 1.1\Omega$
 $\Delta I_{dc} = 3mA$
 $T_u(amb) \leq 60^{\circ}C$

Schematic diagram:

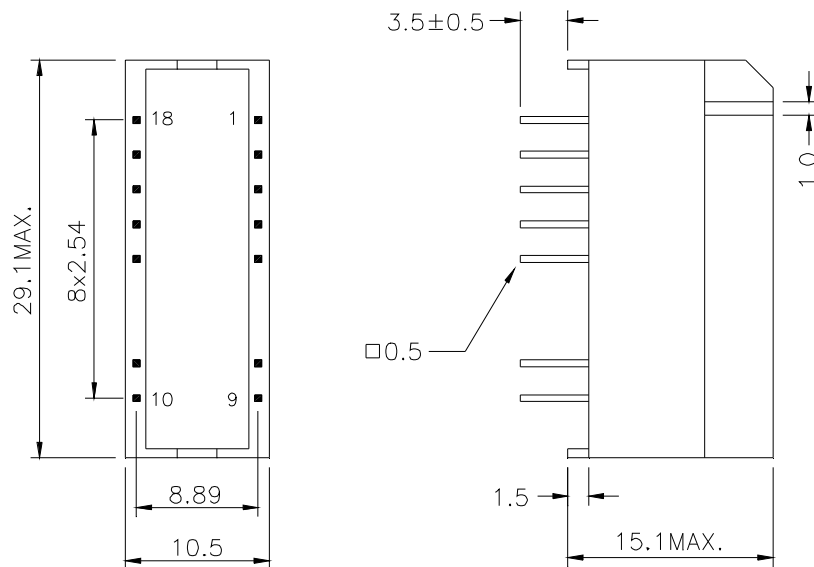


**Approved by Winbond IC chip 6690 and 6692*

Electrical Specification at 25⁰C:

- LI+II ≥ 22mH, (NI+II series), at 10KHz 100mV (core 1,2)
- Polarity and turns ratio tolerance: ±2% (core 1,2)
- Polarity and turns ratio tolerance: ±1% (core 3)
- Ck ≤ 120pF, (NIII to NI+NIV || NII+V, or NI+VI || NII+VII), at 10KHz 100mV (core 1,2)
- Ls I+II ≤ 4.0uH, (NI+II series, NIII shorted), at 100KHz 100mV (core 1,2)
- Ls IV ≤ 0.6uH, (NV, VI, VII shorted), at 100KHz 100mV (core 3)
- LIV = LV = LVI = LVII = 5mH +50%/-30%, at 10KHz 100mV (core 3)
- ZI = ZII ≥ 625Ω, at 20KHz 100mV with ΔIdc = 3mA (core 1,2)
- HI-pot test:
 Up = 1.5KVrms, 3s [NI/II (core 1 + core 2) to NIII (core 1 + core 2)]
 Up = 0.5KVrms, 2s [NIV+V (core 3) + NIII (core 1) to (NVI+VII (core 3) + NIII (core 2)]

Dimension:



NOTE: Specifications are subject to change without prior notice.

UNIT: mm

Tolerances: ±0.2mm



UNIVERSAL MICROELECTRONICS CO.,LTD.
 TEL: 886-4-23590096 FAX: 886-4-23590129
 http://www.umec-web.com E-mail: business@umec.com.tw

3,27TH RD., TAICHUNG INDUSTRIAL PARK,
 TAICHUNG, TAIWAN, R.O.C

E10-013-C